



STALLMAN & POLLOCK LLP
121 Spear Street, Suite 290
San Francisco, CA 94105
(415) 512-1312

In re Patent Application of: Donald Malcolm MacIntyre

Atty Docket No. MCSP-101

Application No.: 09/045,507

Filed: March 20, 1998

For: CHIP SCALE PACKAGES

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Transmittal herewith is an amendment in the above-identified application.

The fee has been calculated as shown below.

	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
TOTAL	9	MINUS	20		x \$18 =	\$
INDEP.	3	MINUS	3		x \$84 =	\$
FIRST PRESENTATION OF MULTIPLE DEP CLAIMS					+ \$280	\$
TOTAL						\$

Small Entity 50% Filing Fee Reduction (if applicable) \$

- * If the entry in Col. 1 is less than the entry in Col. 2, write "0" in Col. 3
** If the "Highest Number Previously Paid For" IN THIS SPACE is less than 20, write "20" in this space.
*** If the "Highest Number Previously Paid For" IN THIS SPACE is less than 3, write "3" in this space. The "Highest Number Previously Paid For" (Total or Independent is the highest number found from the equivalent box in Col. 1 of a prior amendment or the number of claims originally filed.)

- ☐ No additional fee is required.
- ☒ Applicant(s) hereby petition(s) for a one-month extension of time in which to file the present response and enclose(s) herewith the necessary fee to accompany this petition. A check in the amount of \$55.00 is attached.
- ☒ Please charge any additional fees, including any fees necessary for extensions of time or credit overpayment to Deposit Account No. 50-1703, under Order No. 50-1703.
A duplicate copy of this sheet is enclosed.

STALLMAN & POLLOCK LLP

Dated: 9-26-2003

By: Michael J. Pollock

Michael J. Pollock (Reg. No. 29,098)
Attorneys for Applicant(s)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on September 26, 2003.

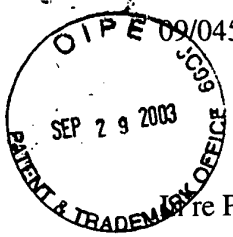
Dated: 09/26/03

By: Lana T. Brenner

Lana T. Brenner

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09/045,507

PATENT

-1-

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re Patent Application of

Donald Malcolm MacIntyre

Application No.: 09/045,507

Filed: March 20, 1998

For: CHIP SCALE PACKAGES

Group Art Unit: 2814

Examiner: D. Wille

**RESPONSE TO OFFICE ACTION
MAILED MARCH 31, 2003**

121 Spear Street, Suite 290
San Francisco, CA 94105
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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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STALLMAN & POLLOCK LLP

Dated: 09/26/2003

By: [Signature]

LANA T. BRENNER

Sir:

Please amend the above-identified application as follows:

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Atty Docket No.: MCSP-101

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TECHNOLOGY CENTER 2800
10/03/2003 10:22:51
00000094 00045507
101 FC:2251

IN THE TITLE

Please delete the current title of the application and substitute the following new title:

--WAFER SCALE STRUCTURE FOR PACKAGING INTEGRATED
CIRCUITS--.

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